

MOSFETs Silicon N-channel MOS (U-MOS^Ⅷ-H)

TPW4R50ANH

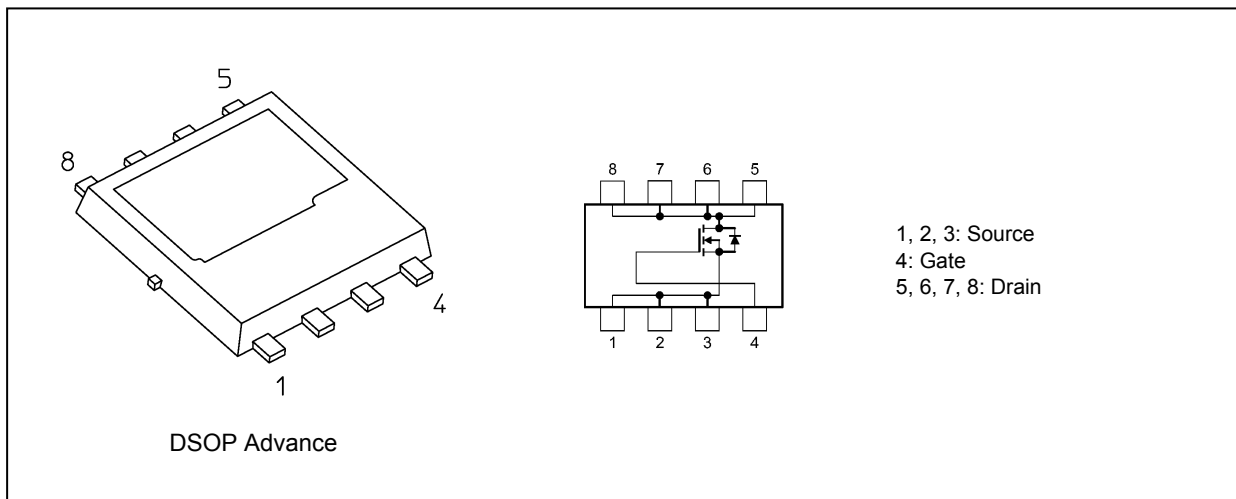
1. Applications

- DC-DC Converters
- Switching Voltage Regulators
- Motor Drivers

2. Features

- (1) High-speed switching
- (2) Small gate charge: $Q_{SW} = 22 \text{ nC (typ.)}$
- (3) Low drain-source on-resistance: $R_{DS(ON)} = 3.7 \text{ m}\Omega \text{ (typ.)}$ ($V_{GS} = 10 \text{ V}$)
- (4) Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A (max)}$ ($V_{DS} = 100 \text{ V}$)
- (5) Enhancement mode: $V_{th} = 2.0 \text{ to } 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1.0 \text{ mA}$)

3. Packaging and Internal Circuit



Start of commercial production

2014-09

4. Absolute Maximum Ratings (Note) ($T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	100	V
Gate-source voltage	V_{GSS}	± 20	
Drain current (DC) ($T_c = 25\text{ }^\circ\text{C}$) (Bottom drain)	I_D	92	A
Drain current (pulsed) ($t = 100\text{ }\mu\text{s}$)	I_{DP}	400	A
Power dissipation ($T_c = 25\text{ }^\circ\text{C}$) (Bottom drain)	P_D	142	W
Power dissipation	P_D	2.5	W
Power dissipation	P_D	0.8	W
Single-pulse avalanche energy	E_{AS}	125	mJ
Single-pulse avalanche current	I_{AS}	92	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance Bottom drain ($T_c = 25\text{ }^\circ\text{C}$)	$R_{th(ch-c)}$	0.88	$^\circ\text{C/W}$
Channel-to-case thermal resistance Top source ($T_c = 25\text{ }^\circ\text{C}$)	$R_{th(ch-c)}$	0.93	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance ($T_a = 25\text{ }^\circ\text{C}$)	$R_{th(ch-a)}$	50	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance ($T_a = 25\text{ }^\circ\text{C}$)	$R_{th(ch-a)}$	156	$^\circ\text{C/W}$

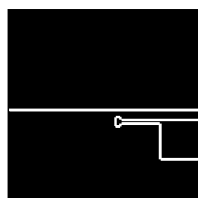
Note 1: Ensure that the channel temperature does not exceed $150\text{ }^\circ\text{C}$.

Note 2: Limited by silicon chip capability.

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

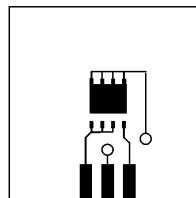
Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: $V_{DD} = 60\text{ V}$, $T_{ch} = 25\text{ }^\circ\text{C}$ (initial), $L = 16\text{ }\mu\text{H}$, $I_{AS} = 92\text{ A}$



FR-4
25.4 × 25.4 × 1.6
(Unit: mm)
2 oz copper

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



FR-4
25.4 × 25.4 × 1.6
(Unit: mm)
2 oz copper

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	100	—	—	V
	$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	65	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 1.0\text{ mA}$	2.0	—	4.0	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 46\text{ A}$	—	3.7	4.5	$\text{m}\Omega$

6.2. Dynamic Characteristics ($T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	4000	5200	pF
Reverse transfer capacitance	C_{rss}		—	31	63	
Output capacitance	C_{oss}		—	700	—	
Gate resistance	r_g	—	—	1.0	1.5	Ω
Switching time (rise time)	t_r	See Fig. 6.2.1	—	9.6	—	ns
Switching time (turn-on time)	t_{on}		—	25	—	
Switching time (fall time)	t_f		—	13	—	
Switching time (turn-off time)	t_{off}		—	52	—	

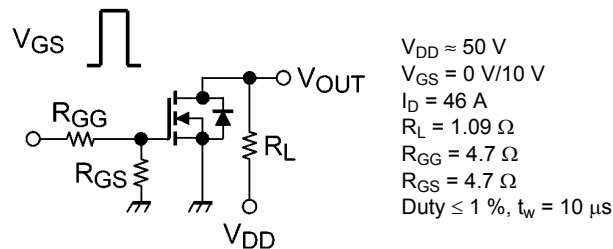


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 50\text{ V}, V_{GS} = 10\text{ V}, I_D = 46\text{ A}$	—	58	—	nC
Gate-source charge 1	Q_{gs1}		—	22	—	
Gate-drain charge	Q_{gd}		—	12	—	
Gate switch charge	Q_{SW}		—	22	—	

6.4. Source-Drain Characteristics ($T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 6)	I_{DRP} ($t = 100\ \mu\text{s}$)	—	—	—	400	A
Diode forward voltage	V_{DSF}	$I_{DR} = 92\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V
Reverse recovery time	t_{rr}	$V_R = 50\text{ V}, I_{DR} = 23\text{ A},$ $V_{GS} = 0\text{ V}, -dI_{DR}/dt = 100\text{ A}/\mu\text{s}$	—	63	—	ns
Reverse recovery charge	Q_{rr}		—	104	—	nC

Note 6: Ensure that the channel temperature does not exceed $150\text{ }^\circ\text{C}$.

7. Marking

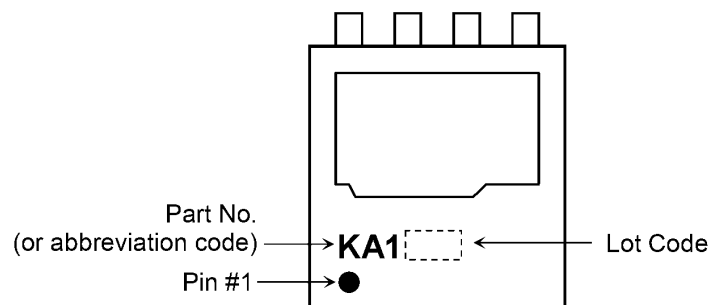


Fig. 7.1 Marking

8. Characteristics Curves (Note)

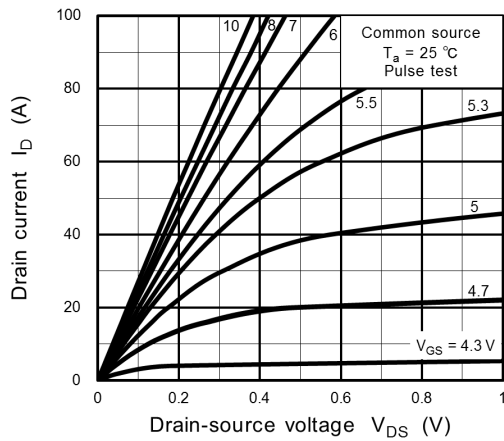


Fig. 8.1 $I_D - V_{DS}$

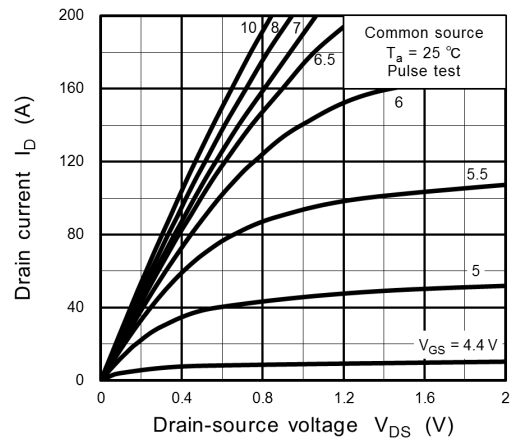


Fig. 8.2 $I_D - V_{DS}$

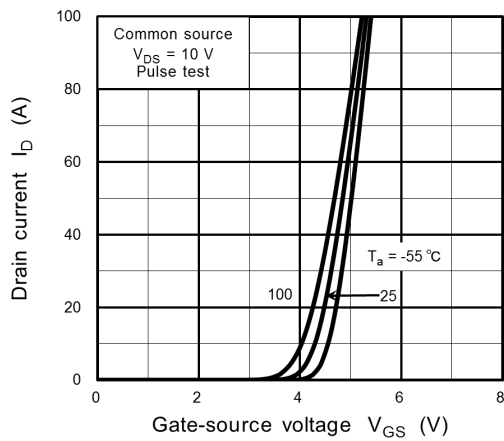


Fig. 8.3 $I_D - V_{GS}$

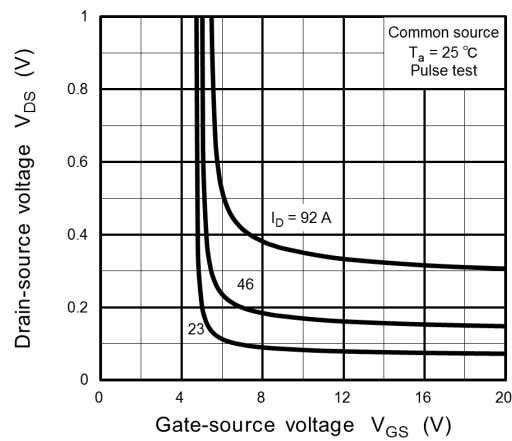


Fig. 8.4 $V_{DS} - V_{GS}$

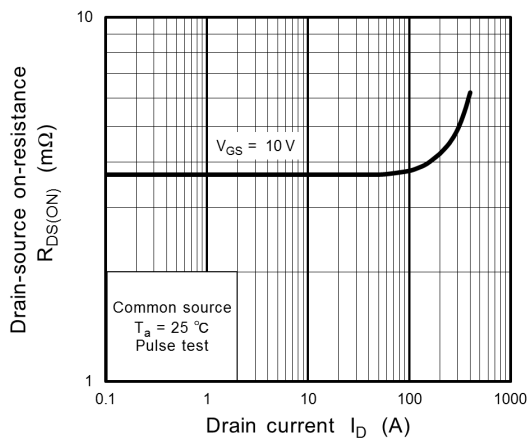


Fig. 8.5 $R_{DS(ON)} - I_D$

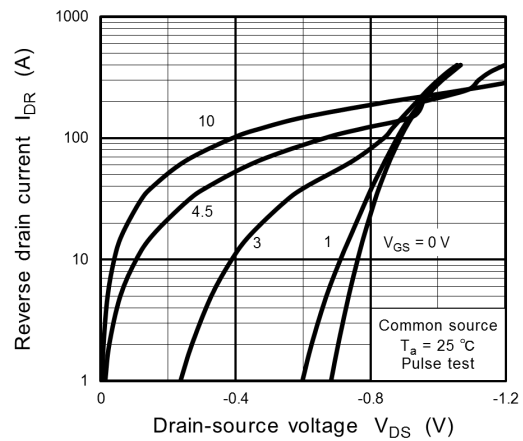


Fig. 8.6 $I_{DR} - V_{DS}$

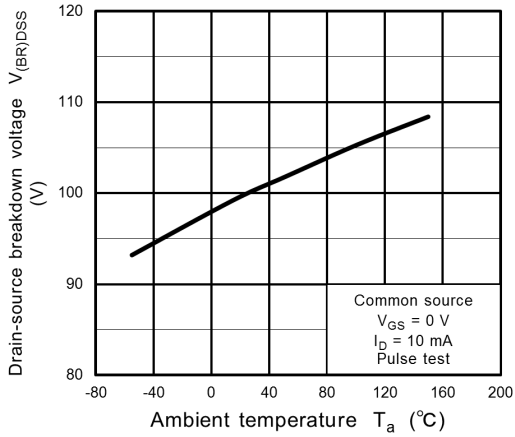


Fig. 8.7 $V_{(BR)DSS} - T_a$

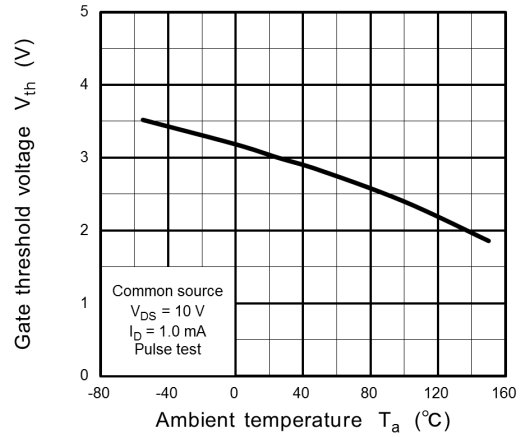


Fig. 8.8 $V_{th} - T_a$

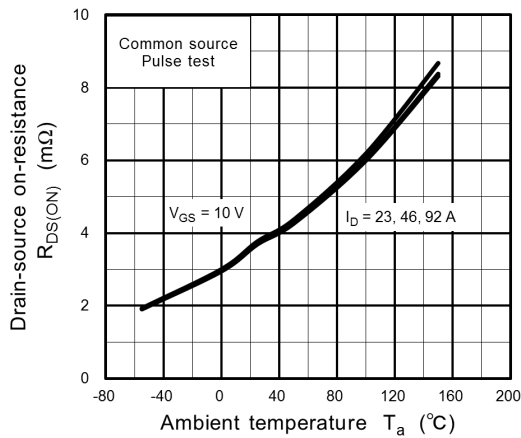


Fig. 8.9 $R_{DS(ON)} - T_a$

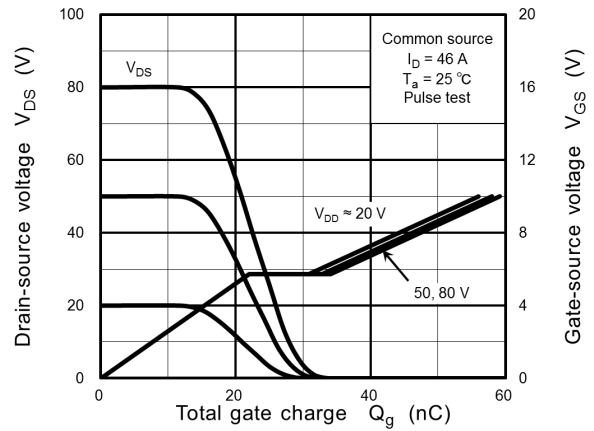


Fig. 8.10 Dynamic Input/Output Characteristics

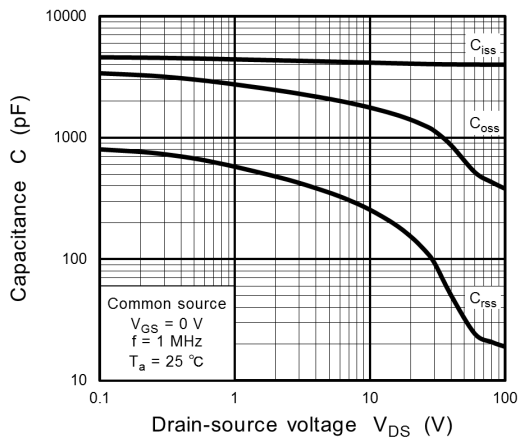


Fig. 8.11 Capacitance - V_{DS}

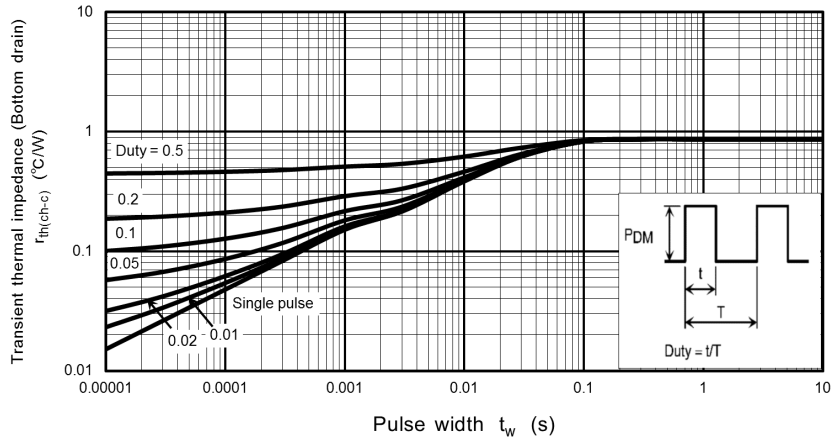


Fig. 8.12 $r_{th} - t_w$ (Bottom drain)
(Guaranteed Maximum)

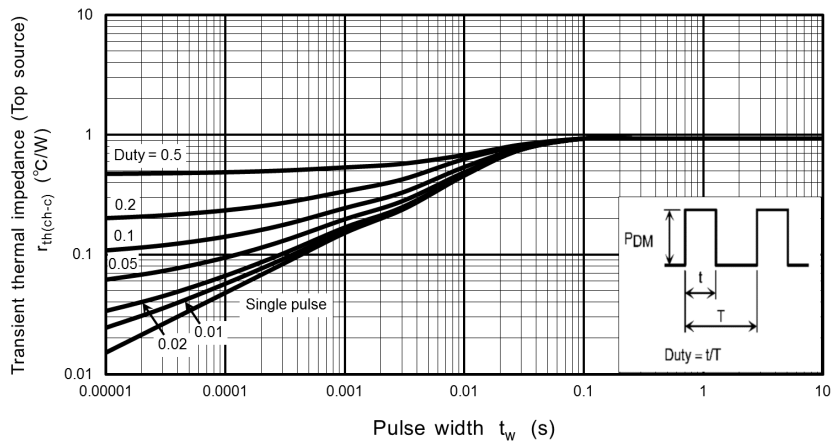


Fig. 8.13 $r_{th} - t_w$ (Top source)
(Guaranteed Maximum)

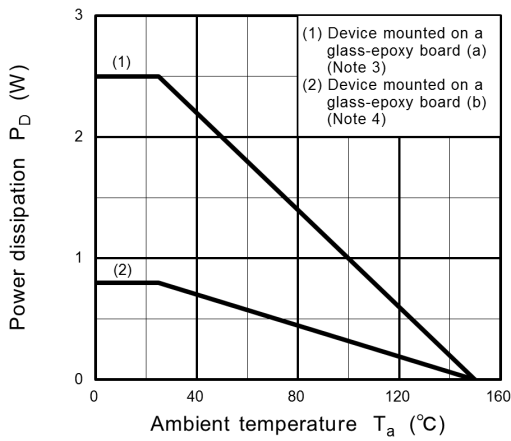


Fig. 8.14 $P_D - T_a$
(Guaranteed Maximum)

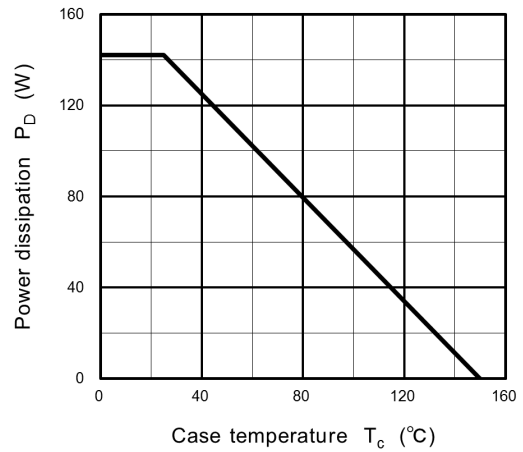


Fig. 8.15 $P_D - T_c$ (Bottom drain)
(Guaranteed Maximum)

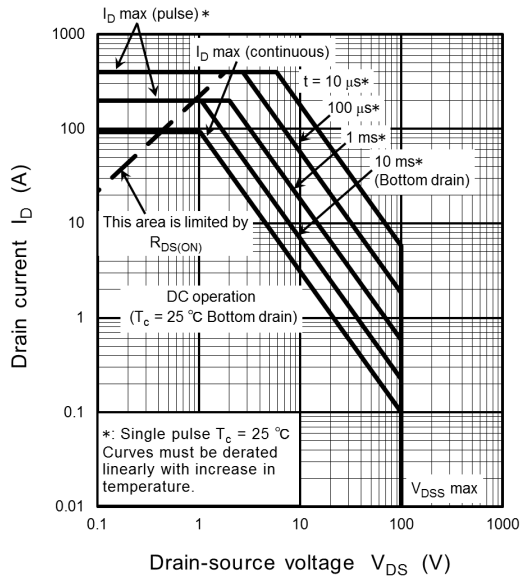


Fig. 8.16 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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